



This is a summary report about issues found in your data during DFA/DFM checks. To see details or to resolve any Open issues, kindly log in to your Customer Portal and go to Project SPX19432

ISSUE	ISSUE TOPIC	ISSUE DETAILS
IST138180 Mon, 09/16/2019 10:47 AM RESOLVED	Assembly- Mounting orientation confirmation needed	For the DFA checks, we need you to advise if the marked pad of components mentioned below is pin-1: SW1 (Line Item# 73) [MPN: CHP-081TA]
		Capture.JPG
IST138179 Mon, 09/16/2019 10:47 AM RESOLVED	Assembly- No Polarity marking	We need you to advise for the PIN1 marking for below mentioned components as it is missing in silkscreen layer. X1 (Line Item# 95) [MPN: ASE-12.000MHZ-LC-T]
		X1.jpg
IST138178 Mon, 09/16/2019 10:47 AM RESOLVED	Assembly- Cathode Mark confirmation needed	We need you to advise if the marked pad of components mentioned below is cathode: D27 (Line Item# 22) [MPN: LH R974-LP-1] D8,D2,D26,D4,D5,D6,D7,D9,D10,D11,D12,D13 (Line Item# 24) [MPN: LG R971-KN-1]
		INIT  Description  Solve the state of the st
		D27.jpg D8.jpg
IST137318 Mon, 09/09/2019 10:37 PM RESOLVED	Data Discrepancy- Gerber related	While performing DRC on your order, we observed stubs(Un-terminated traces) on inner layer4 at 5 locations. Please confirm can we proceed as is or else advise. Screen shot attached for your reference

		160832-stubs on layer4.png
IST137275 Mon, 09/09/2019 5:53 PM RESOLVED	Data Discrepancy- Manufacturing specs	@JeffAfter running DRC on the design, we have observed an issue. One of the documents received by our assembly team calls for bevelling of boards at the bottom edge of the board. As discussed with you over phone, there is no beveling required as copper is very near to the board edge in layer 2,7 & 8 and beveled edges will expose the copper. As you don't want the copper to be pulled back, you have agreed to without beveling. Please reply for the confirmation.
IST137183 Mon, 09/09/2019 12:52 PM RESOLVED	Assembly- Mechanical/Package dimension details needed	For the DFA checks, we need you to provide the mechanical dimensional datasheet (Footprint information) of components mentioned below for footprint verification as we could not find one.  U15 (Line Item# 79) [MPN: LFE5UM5G-85F-8BG756C] This datasheet must contain the mechanical dimensions of the component such as pitch, length, width etc.
IST137182 Mon, 09/09/2019 12:52 PM RESOLVED	Assembly- BOM components missing in Gerber and placement files	DFA checks of your files show that components mentioned below are present in BOM but missing in Gerber files and placement files. Kindly review and advice assembly location.  J8,J14 (Line Item# 35) [MPN: 9774025151R]
IST137180 Mon, 09/09/2019 12:52 PM RESOLVED	Assembly- Foot Print mismatch	DFA checks of your files show a footprint mismatch of components J1 (Line Item# 29) [MPN: PJ-037A] in GERBER files w.r.t. mechanical dimensions as per datasheet. As shown in image, Gerber footprint is not matching with recommended land pattern. Kindly provide an alternate part# for this or advise if we need to make component DNI.
		j1.JPG
IST137106 Fri, 09/06/2019 9:57 PM RESOLVED	Assembly- Other	For the DFA checks shows most of the components are missing in XY data, but present in BOM. Please find the attached report for your Reference. Kindly review and provide us the updated XY data, hence we can proceed with your jobs.  Until then, your order is kept On-Hold for DFA checks.
		XY Report.xlsx
IST137090 Fri, 09/06/2019	Assembly- IBOM issue resolution not	As per information received to us during online quotation, your boards are to be cleaned after assembly. But the below components are Non-Washable. Please

8:01 PM RESOLVED	complete	advise if we must follow clean process or proceed with clean such that the non-washable components will be soldered manually after assembly. SW1 (Line item# 73 MPN: CHP-081TA)
IST137082 Fri, 09/06/2019 7:19 PM RESOLVED	Assembly- XY data missing	Pick-and-place file is missing in your provided set of gerber files. Please provide us the pick-and-place file containing reference designators, assembly side, X location, Y location and rotation information so that we can validate your gerber files for assembly. Until then, your order is kept On-Hold for DFA checks.
IST137063 Fri, 09/06/2019 5:45 PM RESOLVED	Design Issue- Gerber related	While performing DFM validation on your order we observed that 3.042 mil spacing on your design (top and bottom layer) but web spec calls 4 mil spacing. Also less than 4Mils spacing is not qualified for Web orders. This may required custom quote for which our sales team will get in touch with you.
		bottom layer.png top layer.png
IST137059 Fri, 09/06/2019 5:45 PM RESOLVED	Design Issue- Solder mask related	While performing DFM validation we observed that, Gang mask opening is provided in both solder mask layer. Find attached snap shot for your quick reference. This job is going to be assembled at our facility and we prefer individual mask opening. Please allow us to remove Gang relief and go ahead with individual mask opening. Please confirm.
		bottom mask.png top mask.png
IST137053 Fri, 09/06/2019 5:45 PM RESOLVED	Design Issue- Gerber related	While performing DFM validation on your order, we observed few un-terminated traces (stubs) in top and bottom layer. Please confirm whether this is by design or else advise. Attached snap shot for your quick reference.
IST137050 Fri, 09/06/2019	Other	While performing DFM validation, we observed finger like features are present but bevel information is not provided. Can we proceed as per standard (15 mils bevel depth with 45 degree angle)? Please confirm.
5:45 PM		
5:45 PM RESOLVED		

Fri, 09/06/2019 5:45 PM RESOLVED	Solder mask related	While DFM validation, we observed partial mask opening for rectangular pad at one location in top mask layer. Find Enclosed snap shot for your quick reference. Can we provide complete mask opening at this location(Pad size+4Mils) OR would you like us to proceed as is? Please confirm.
		top maks.png
IST137041 Fri, 09/06/2019 5:45 PM RESOLVED	Design Issue- Drill related	While performing DFM validation we observed that, web spec calls for number of holes per board: 120, but gerber data received has 3367 number of holes. Can we proceed as per gerber data? Please confirm.
IST137030 Fri, 09/06/2019 5:45 PM RESOLVED	Missing information- Type of Gold/Gold thickness	While performing DFM validation, we observed finger like features are present but web Spec calls for gold finger as "None". Please confirm whether you require hard gold plating for the fingers or you want the whole board to be ENIG finish.  FYI: In case of hard gold plating requirement for the fingers, we need to revise the quote for which our sales team will be in touch with you.
		Screenshot.png
IST137024 Fri, 09/06/2019 5:45 PM RESOLVED	Design Issue- Gerber related	While performing DFM validation on your order we observed, your data contain 12 slots(11 plated and 1 non-plated) but as per web spec only 3 plated and 7 non-plated slots are allowed. This may require to revise your quote for which our sales team will be in touch with you.